

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/148,723
Priority Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Priority Group Art Unit 3729
Priority Examiner D. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

RESPONSE TO FEBRUARY 27, 2001 OFFICE ACTION
PRELIMINARY AMENDMENT TO ACCOMPANY REQUEST FOR
CONTINUED EXAMINATION (RCE) TRANSMITTAL FILING

To: BOX RCE
Assistant Commissioner for Patents
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D.
Tel. 509-624-4276; Fax 509-838-3424
Wells, St. John, Roberts, Gregory & Matkin P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3817

Sir:

Responsive to the Final Office Action dated February 27, 2001,
Applicant amends and remarks as follows:

AMENDMENTS

RECEIVED
APR 25 2001
ITC 3700 MAIL ROOM

Cancel
Claims 12, 46 and 47.
Add claims 48-50.
A.D. Tugbang